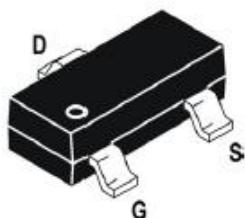


Description**Features**

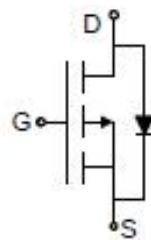
- $V_{DS} = -30V$, $I_D = -2.6A$
- $R_{DS(ON)} < 206 \text{ m}\Omega @ V_{GS} = -2.5V$
 $R_{DS(ON)} < 180 \text{ m}\Omega @ V_{GS} = -4.5V$
 $R_{DS(ON)} < 130 \text{ m}\Omega @ V_{GS} = -10V$
- High Power and Current Handling Capability
- Lead Free Product is Acquired
- Surface Mount Package

Application

- PWM Applications
- Load Switch
- Power Management

Package

SOT-23



Schematic Diagram

Absolute Maximum Ratings ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		-30	V
V_{GSS}	Gate-Source Voltage		± 12	V
I_D	Continuous Drain Current	$T_c = 25^\circ\text{C}$	-2.6	A
		$T_c = 100^\circ\text{C}$	-2.0	
P_D	Power Dissipation	$T_c = 25^\circ\text{C}$	1.2	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		115	$^\circ\text{C}/\text{W}$
T_J , T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$



Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D = -250\mu\text{A}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24\text{V}, V_{GS} = 0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 10\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.4	-0.7	-1.3	V
$R_{DS(\text{on})}$	Static Drain-Source on-Resistance note2	$V_{GS} = -10\text{V}, I_D = -2.6\text{A}$	-	98	130	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -2\text{A}$	-	120	180	
		$V_{GS} = -2.5\text{V}, I_D = -1\text{A}$	-	150	206	
g_{FS}	Forward Transconductance	$V_{DS} = -5\text{V}, I_D = -2.6\text{A}$	-	6	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	-	1021	-	pF
C_{oss}	Output Capacitance		-	134	-	pF
C_{rss}	Reverse Transfer Capacitance		-	83	-	pF
Q_g	Total Gate Charge	$V_{DS} = -15\text{V}, I_D = -2.6\text{A}, V_{GS} = -4.5\text{V}$	-	9.2	-	nC
Q_{gs}	Gate-Source Charge		-	2.1	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	3.3	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -15\text{V}, I_D = -2.6\text{A}, V_{GS} = -10\text{V}, R_{\text{GEN}} = 6\Omega$	-	9	-	ns
t_r	Turn-on Rise Time		-	5	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	36	-	ns
t_f	Turn-off Fall Time		-	16	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current		-	-	-2.6	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_s = -2.6\text{A}$	-	-	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$



3401S/C(文件编号: S&CIC1950)

P-Channel Trench Power MOSFET

Typical Performance Characteristics

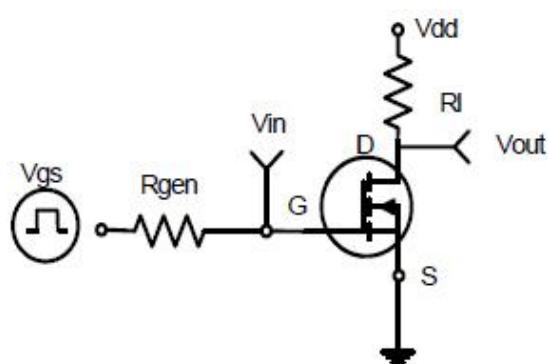


Figure1:Switching Test Circuit

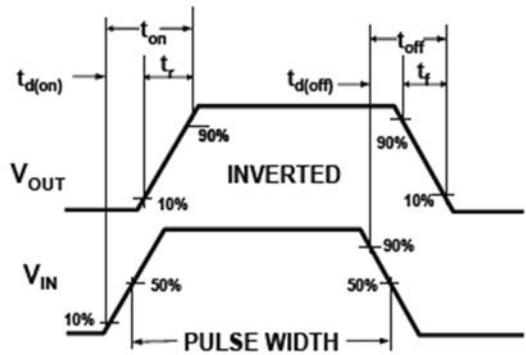


Figure2:Switching Waveforms



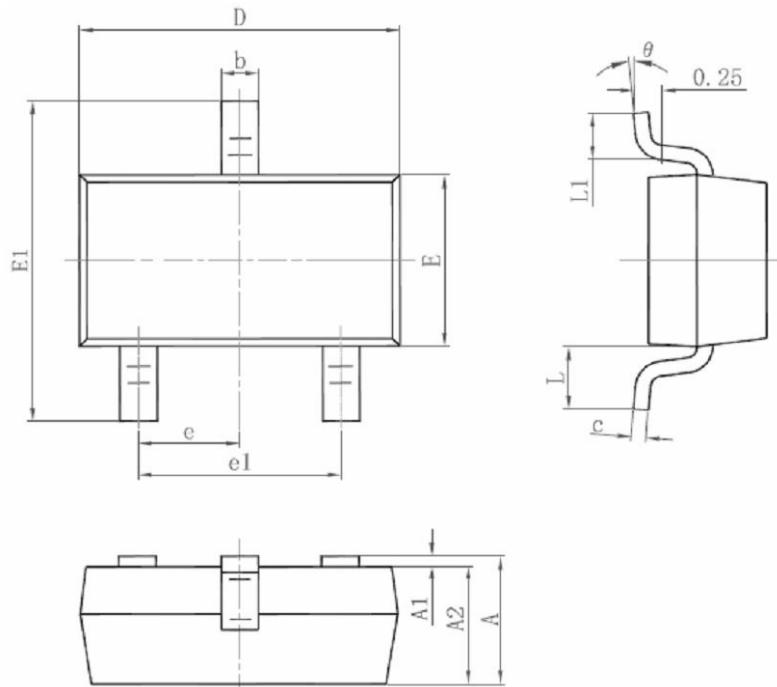
富满微电子集团股份有限公司
FINE MADE MICROELECTRONICS GROUP CO., LTD.

3401S/C(文件编号: S&CIC1950)

P-Channel Trench Power MOSFET

Package Information.

- SOT23-3(小)



符号	毫米		英寸	
	最小	最大	最小	最大
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°